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3D-PEIM Highlights Technology For Increasing Density And Performance Of Power Solutions

The PSMA invites you to attend the fourth biennial International Symposium on 3D Power Electronics Integration and Manufacturing (3D-PEIM-2023). This symposium provides the opportunity to receive an update on the latest technology focused on increasing the density and the performance of power solutions. Discover advances in the integration of design, packaging and manufacturing of 3D power sources. Technical sessions include modeling, active and passive components, substrates, packaging and how to integrate them with 3D manufacturing technologies to create state-of-the-art power sources.

The International 3D Power Electronics Integration and Manufacturing (3D-PEIM) symposium will be held February 1 – 3, 2023 at Florida International University.

The symposium will be held February 1-3, 2023 at Florida International University, Miami, Florida, offering an opportunity to get a “winter warm-up” on Florida’s enticing beaches. Technical sponsors of the symposium include Florida International University (FIU), IEEE Electronics Packaging Society (EPS) and PSMA.

Created and supported by the PSMA’s Packaging & Manufacturing Committee, 3D-PEIM will feature invited papers highlighted by plenary and keynote addresses and contributed presentations by experts from industry and academia. Speakers will address design, thermal, materials, reliability, and manufacturability issues. There will also be exhibits and an Exhibit Sponsor’s session. Ample opportunities will be provided to network with attendees, speakers and exhibitors.

The symposium will be headlined by an excellent list of plenary speakers comprised of international power technology leaders from industry and academia including

- Fred C. Lee, Virginia Tech, USA, who will present on “PCB based Integrated Magnetics”.
- Professor Katsuaki Suganuma, University of Osaka, Japan, on “Superior heat dissipation by low-pressure Ag sinter joining and real-time AI lifetime prediction for SiC power module”.
- Brandon Passmore, Wolfspeed, on “Finite-Element Predictive Modeling for Power Modules”.
- Mahadevan Iyer, Amkor, on “Emerging Power electronics packaging and system integration for automotive applications”.
- Madhavan Swaminathan, Georgia Tech, on “Integrated Power Delivery for AI Computing: Technology Gaps & Opportunities”.

In addition the program will be comprised of technical sessions run in series over a three-day period. Not a single session should be missed.

The program at a glance will include

- IVR for Computers and Servers; Chair: Siddarth Ravichandran, Chipletz
- Multiphysics Design & Tools; Chair: Rajen Murugan, Texas Instruments
- Additive Manufacturing; Chair: Peter Friedrichs, Infineon
- Manufacturing Technologies; Chair: Jason Rouse, Corning
- Materials I Interconnects & Lead Attachments; Chair: Andy Mackie, Indium

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- Materials II Substrates & Encapsulants; Chair: Ninad Shahane, Texas Instruments
- High Power Module Integration; Chair: Cyril Buttay, Laboratoire Ampère, Lyon
- Thermal Management and Reliability; Chair: Patrick McCluskey, University of Maryland
- Passive Component Integration; Chair: John Bultitude, KEMET
- Low Power & Telemetry; Chair: Shubhendu Bhardwaj, Florida International University
- Tour of FIU Labs; Chair: Markondeyaraj Pulugurtha, Florida International University

The general chair is Markondeyaraj Pulugurtha of Florida International University (FIU). Technical program co-chairs are John Bultitude of Kemet, a Yageo Company, and Vanessa Smet from Georgia Tech.

Registration is now open at Registration - 3D PEIM (3d-peim.org). For additional information visit http://www.3d-peim.org.

You are invited to sign up for partnership tabletop exhibit opportunities. Each exhibit partner has the opportunity to present products at the symposium and on a 3D-PEIM virtual tabletop website page. To learn more and sign up as an exhibit partner, visit http://www.3d-peim.org/sponsors-exhibitors/.

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